



## Description

### JMG N-channel Enhancement Mode Power MOSFET

#### Features

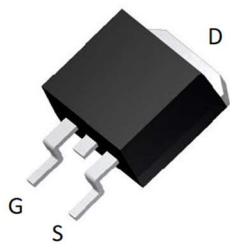
- 85V, 130A  
 $R_{DS(ON)} < 5.2m\Omega @ V_{GS} = 10V$
- Advanced Trench Technology
- Provide Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead free product is acquired

#### Application

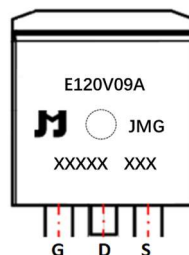
- Load Switch
- PWM Application
- Power management



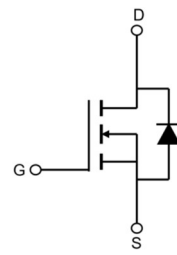
*100% UIS TESTED!*  
*100%  $\Delta V_{ds}$  TESTED!*



TO-263 top view



Marking and pin Assignment



Schematic Diagram

## Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
JMGE120V09A	JMGE120V09A	TAPING	TO-263	13inch	800	4000

## Absolute Maximum Ratings ( $T_C=25^\circ C$ unless otherwise specified)

Symbol	Parameter	Max.	Units
$V_{DSS}$	Drain-Source Voltage	85	V
$V_{GSS}$	Gate-Source Voltage	$\pm 25$	V
$I_D$	Continuous Drain Current	$T_C = 25^\circ C$	130
		$T_C = 100^\circ C$	85
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>	520	A
EAS	Single Pulsed Avalanche Energy <sup>note2</sup>	132	mJ
$P_D$	Power Dissipation	$T_C = 25^\circ C$	184
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.8	$^\circ C/W$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +175	$^\circ C$



## Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	85	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =85V, V <sub>GS</sub> =0V,	-	-	1.0	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±25V	-	-	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2	3	4	V
R <sub>DS(on)</sub>	Static Drain-Source on-Resistance <small>note3</small>	V <sub>GS</sub> =10V, I <sub>D</sub> =30A	-	4	5.2	mΩ
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHz	-	3750	-	pF
C <sub>oss</sub>	Output Capacitance		-	2300	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	340	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =68V, I <sub>D</sub> =30A, V <sub>GS</sub> =10V	-	60	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	22	-	nC
Q <sub>gd</sub>	Gate-Drain("Miller") Charge		-	14	-	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =40V, I <sub>D</sub> =30A, R <sub>G</sub> =3Ω, V <sub>GS</sub> =10V	-	20	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	38	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	53	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	15	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	130	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	520	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =30A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I <sub>F</sub> =30A, di/dt=100A/μs	-	34	-	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge		-	200	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

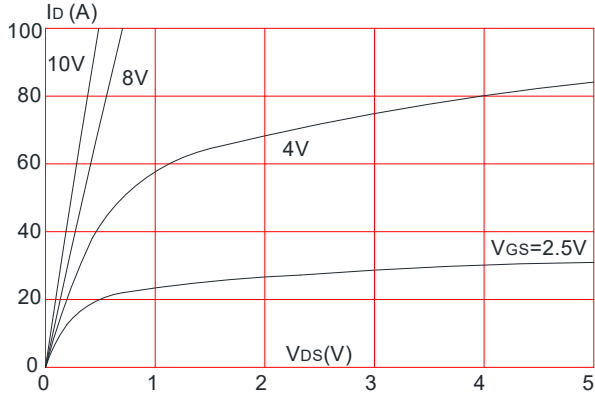
2. EAS condition : T<sub>J</sub>=25°C, V<sub>DD</sub>=50V, V<sub>G</sub>=10V, L=0.5mH, R<sub>G</sub>=25Ω, I<sub>AS</sub>=23A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

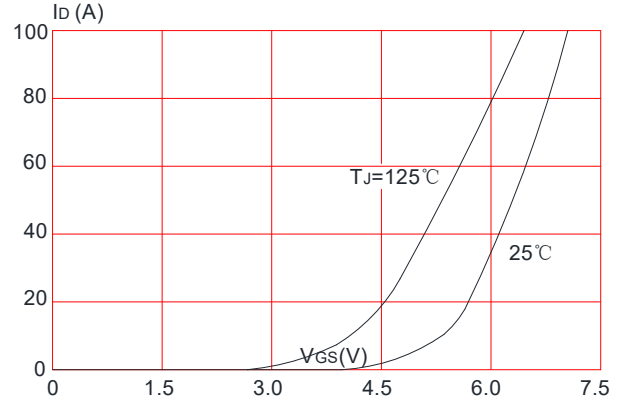


## Typical Performance Characteristics

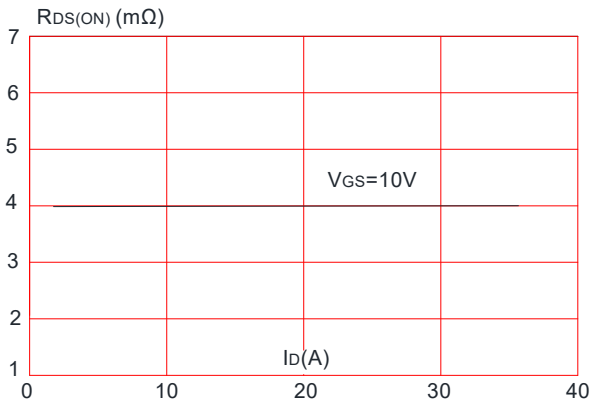
**Figure 1:** Output Characteristics



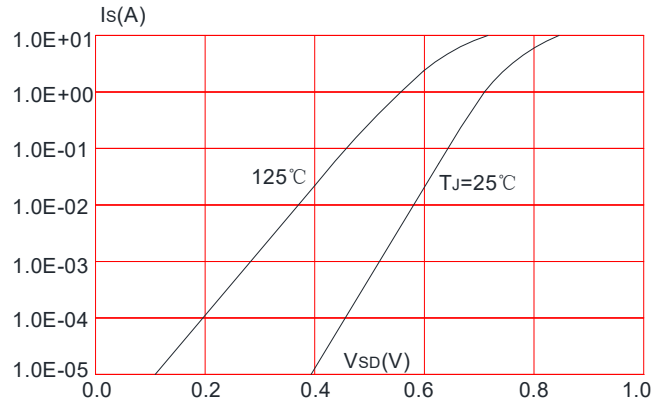
**Figure 2:** Typical Transfer Characteristics



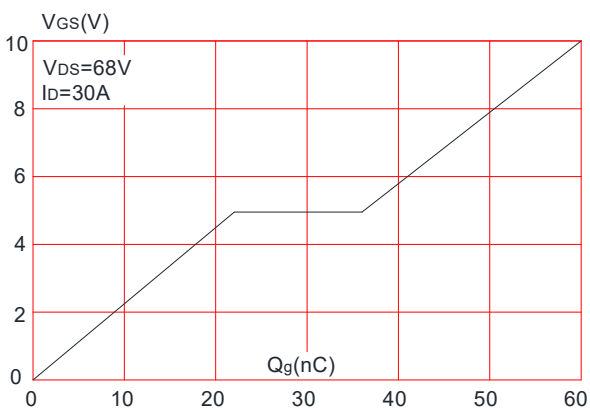
**Figure 3:** On-resistance vs. Drain Current



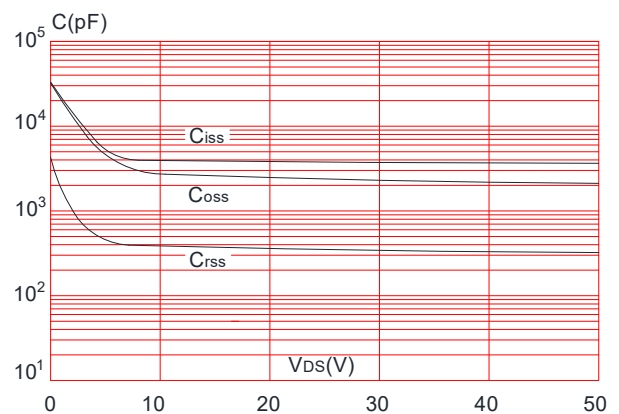
**Figure 4:** Body Diode Characteristics



**Figure 5:** Gate Charge Characteristics

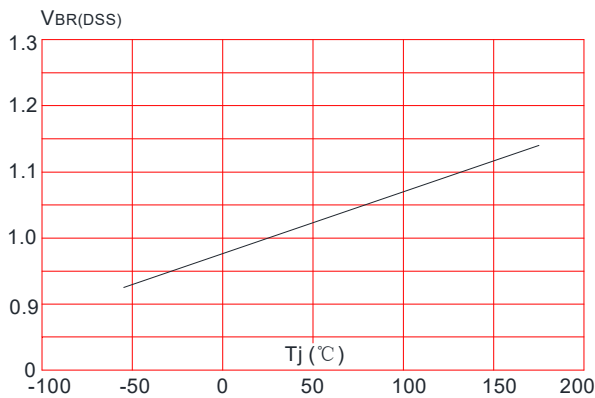


**Figure 6:** Capacitance Characteristics

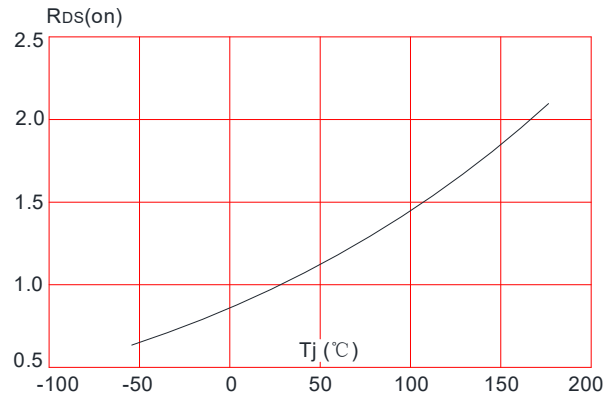




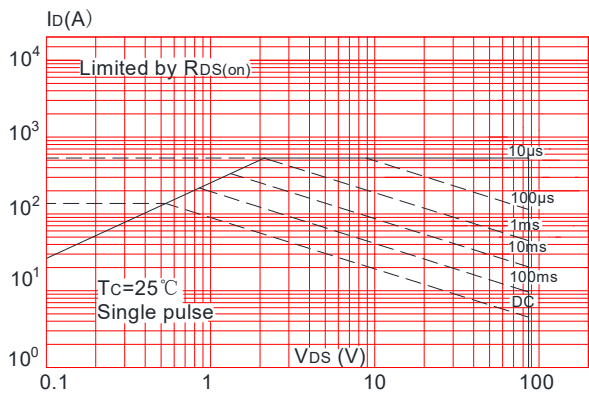
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



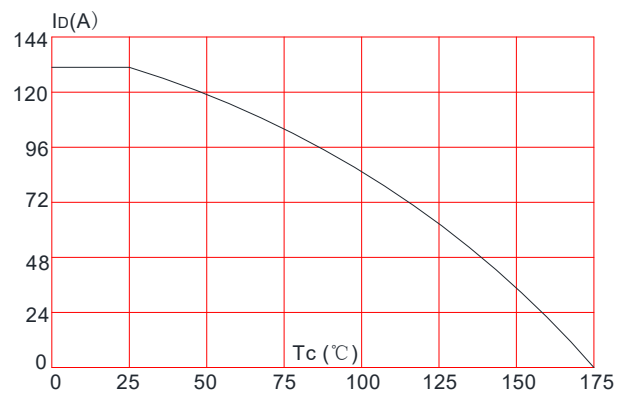
**Figure 8:** Normalized on Resistance vs. Junction Temperature



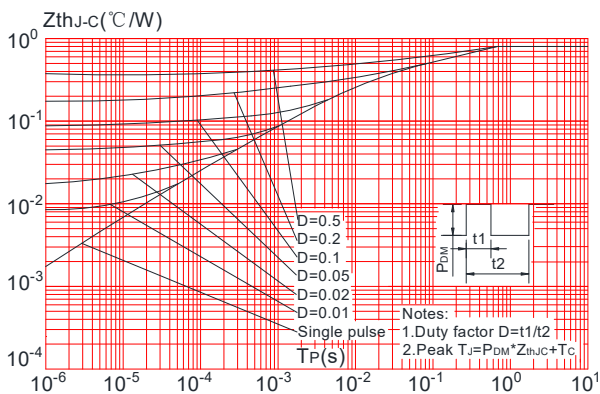
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



## Test Circuit



Figure 1: Gate Charge Test Circuit & Waveform

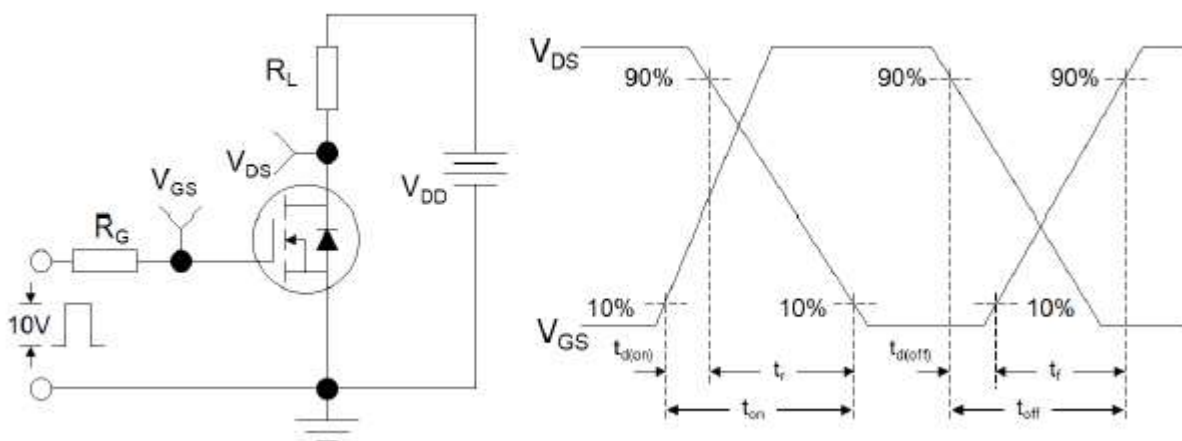


Figure 2: Resistive Switching Test Circuit & Waveforms

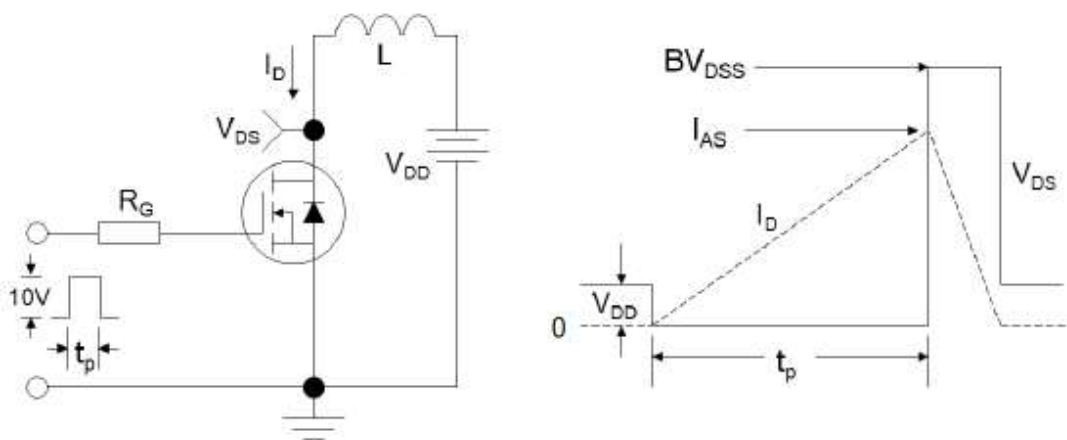
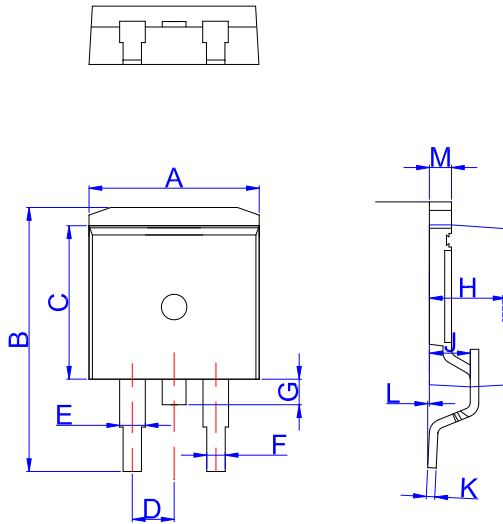


Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms

## Package Mechanical Data-TO-263



TO-263

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	9.90		10.20	0.390		0.402
B	14.70		15.80	0.579		0.622
C	9.4		9.6	0.37		0.378
D		2.54			0.100	
E	1.20		1.40	0.047		0.055
F	0.75		0.85	0.029		0.033
G			1.75			0.069
H	4.40		4.70	0.173		0.185
J	2.30		2.70	0.091		0.106
K	0.38		0.55	0.015		0.022
L	0	0.10	0.25	0	0.004	0.010
M	1.25		1.35	0.049		0.053

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